

## SPECIFICATION

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# **OLED SPECIFICATION**

### Model No:

## REX006448AWPP3N00000

## New Product only for reference

## **CUSTOMER:**

APPROVED BY			
PCB VERSION			
DATE			
FOR CUSTOMER USE	ONLY		
	10		
SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
Release DATE:			



## 1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2016/09/29		First release
A	2019/09/02		Modify Precautions in
			use of OLED Modules



# Contents

- 1. General Specification
- 2. Module Classification Information
- **3.Interface Pin Function**
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- 8.OLED Lifetime
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- 10.Inspection specification
- 11.Precautions in use of OLED Modules



### **1.General Specification**

The Features is described as follow:

- Module dimension: 18.46 × 18.10 × 1.3 mm
- Active area: 13.42 × 10.06 mm
- Dot Matrix: 64 x 48 Dots
- Pixel size: 0.185 × 0.185 mm
- Pixel pitch: 0.210 × 0.210 mm
- Display Mode: Passive Matrix
- Drive Duty: 1/48 Duty
- Display Color: White
- IC: SSD1306BZ



## 2.Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	E	Х	006448	А	W	Р	Р	3	Ν	0	0	0	00

1	Brand : Raystar Optronics Inc.							
2	E : OLED							
3	Display Type : C $\rightarrow$ Character, G $\rightarrow$ Graphic , T $\rightarrow$ TAB ,X $\rightarrow$ COG , H $\rightarrow$ COG (with Frame)							
4	Dot Matrix : 64*48							
5	Series							
		A : Amber	R : Red	C : Full Color				
6	Emitting Color	B : Blue	W: White					
6	Emitting Color	G : Green	Y : Yellow					
		S : Sky Blue	X : Dual Color					
7	Polarizer	P: With Polarizer;	N: Without Polarizer					
1	Polarizer	A : Anti-glare Polar	rizer					
8	Display Mode	P : Passive Matrix	; N: Active Matrix					
9	Driver Voltage	3:3.0~3.3V ; 5	:5.0V					
10	Touch Panel	N: Without touch p	panel; T: With touch par	nel				
11	Product type	0 : Standard 1 : Sunlight Reada 2 : Transparent OL 3 : Flexible OLED 4 : OLED Lighting	ED (TOLED)					
12	Inspection Grade	0 : Standard 2 : B grade C : Automotive grade Y : Consumer grade						
13	Interface	0 : Default ; F : FP	C;H:Hotbar;D:De	emo Kit				
14	Serial No.	Serial number(00~2	ZZ)					



### **3.Interface Pin Function**

No.	Symbol	Function						
1	ESD-GND	It should be connected to ground.						
2	C2N	Positive Terminal of the Flying Inverting Capacitorr Negative Terminal of						
3	C2P					acitors are requir		
4	C1P	between the	e terminals	s. They must b	e floated whe	n the converter is	s not	
5	C1N	used.						
6	VBAT	This is the p converter. It	ower sup must be	connected to e	internal buffer external source	of the DC/DC vo when the conve onverter is not use	erter is	
7	VSS	This is a gro	ound pin.					
8	VDD	Power supp	ly pin for	core logic ope	ration.	· · · · · · · · · · · · · · · · · · ·		
9	BS1	MCU bus in	terface se	election pins.				
10	BS2	SSD1306B Pin Name BS0 BS1 BS2	I <sup>2</sup> C Interface 0 1 0	6800-parallel interface (8 bit) 0 0 1	Bus Interface 8080-parallel interface(8 bit) 0 1 1	PIN Selection 4-wire Serial interface 0 0 0		
11	CS#		ne chip se	elect input. The when CS# is p	•	ed for MCU		
12	RES#			troller and Driv al input. When		initialization of th	e chip is	
13	D/C#	VDD), the d D[7:0] is trea transferred t command re In I2C mode	This is Data/Command control pin. When it is pulled HIGH (i.e. connect to VDD), the data at D[7:0] is treated as data. When it is pulled LOW, the data at D[7:0] will be transferred to the command register. In I2C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to					
14	$\mathbf{R}$ $\mathbf{N}\mathbf{N}\mathbf{T}$	This is read When interfa Read/Write	acing to a (R/W#) out. Read t to VDD)	6800-series n mode will be o	nicroprocesso	the MCU interfac r, this pin will be en this pin is pulle	used as	

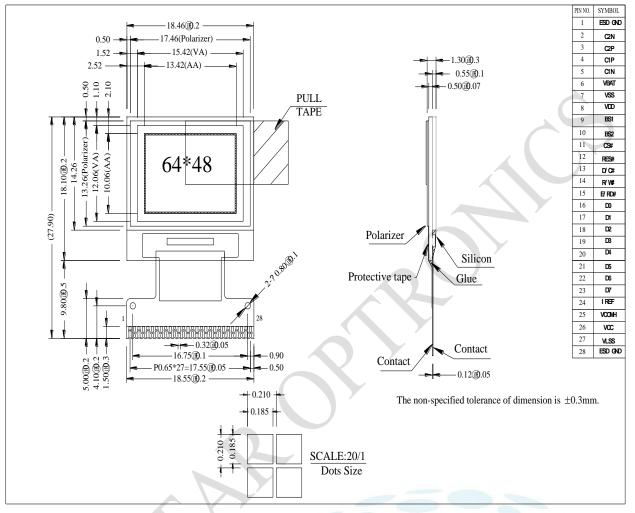
00



		When interfacing to a 6800-series microprocessor, this pin will be used as
		the Enable (E) signal.
		Read/write operation is initiated when this pin is pulled HIGH (i.e. connect to VDD) and the chip
15	E/RD#	is selected.
		When connecting to an 8080-series microprocessor, this pin receives the Read (RD#) signal. Read
		operation is initiated when this pin is pulled LOW and the chip is selected.
		When serial or I2C interface is selected, this pin must be connected to VSS
		These are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When
		serial interface mode is selected, D0 will be the serial clock input: SCLK;
16~23	D0~D7	D1 will be the serial data input: SDIN.
		When I2C mode is selected, D2, D1 should be tied together and serve as
		SDAout, SDAin in
		application and D0 is the serial clock input, SCL.
		This is segment output current reference pin. When external IREF is used, a resistor should be connected between this
		pin and VSS to maintain
24	IREF	the IREF current at a maximum of 30uA. Please refer to Figure 7-15 for the
27		details of resistor
		value.
		When internal IREF is used, this pin should be kept NC.
		Voltage Output High Level for COM Signal
25	VCOMH	This pin is the input pin for the voltage output high level for COM signals. A
		capacitor should be connected between this pin and VSS.
		Power Supply for OEL Panel
		This is the most positive voltage supply pin of the chip. A stabilization
26	VCC	capacitor should be connected between this pin and VSS when the
		converter is used. It must be connected to external source when the
07		converter is not used.
27 28	VLSS ESD GND	This is an analog ground pin. It should be connected to VSS externally. It should be connected to ground.
20		
	Υ 7	
	Y	

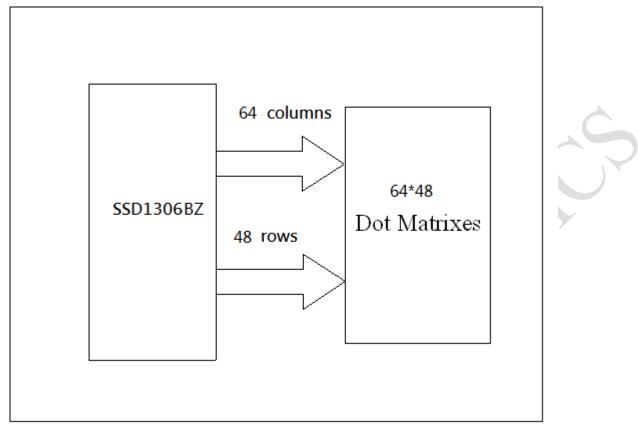


### 4.Contour Drawing & Block Diagram

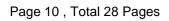




#### FUNCTION BLOCK DIAGRAM



\*For more information, please refer to Application Note provided by Raystar Optronics.





### **5.Absolute Maximum Ratings**

Parameter	Symbol	Min	Max	Unit	Notes	
Supply Voltage for Logic	VDD	0	4	V	1,2	
Supply Voltage for Display	VCC	0	15	V	1,2	C
Operating Temperature	TOP	-40	+80	°C	- (	
Storage Temperature	TSTG	-40	+80	°C	-	

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



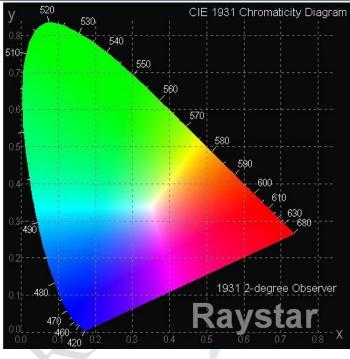
### **6.Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	—	7.0	7.5	8.0	×
Input High Volt.	VIH	—	0.8×VDD	-	VDDIO	V
Input Low Volt.	VIL	—	0	~	0.2×VDD	V
Output High Volt.	VOH	—	0.9×VDD		VDDIO	V
Output Low Volt.	VOL	-	0		0.1×VDD	V
50% Check Board operating Current	ICC	VCC=7.5V		6.0	13.0	mA



## **7.Optical Characteristics**

ltem	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	—	160	_	-	deg
	(V)θ     -       (H)φ     -       CR     Dark       T rise     -       T fall     -       heck Board Brightness     (CIE1		160	_		deg
Contrast Ratio	CR	Dark	2000:1	-	-	-
Response Time	T rise	—	_	10		μs
	T fall	—	-	10		μs
Display with 50% check E	Board Brightness		100	120	_	cd/m2
CIEx(White)	(CIE1931)	0.26	0.28	0.30	—	
CIEy(White)		(CIE1931)	0.30	0.32	0.34	_





### 8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	20,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



## 9.Reliability

### Content of Reliability Test

Environmenta	l Test		
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 240hrs	- (
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40℃ 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60℃,90%RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C25°C80°C 30min 5min 30min 1 cycle	-40℃/80℃ 100 cycles	
Mechanical Tes	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	-
Others			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	

\*\*\* Supply voltage for OLED system =Operating voltage at  $25^\circ\!\mathrm{C}$ 



#### Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

#### **Evaluation criteria**

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

#### **APPENDIX:**

#### **RESIDUE IMAGE**

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



## **10.Inspection specification**

NO	Item	Criterion					AQL		
01	Electrical	1.1 Missing vertical, horizontal segment, segment contrast							
	Testing	defect.	<b>,</b>						
		1.2 Missing chai	acter, dot	t or i	con.				
			1.3 Display malfunction.						
			.4 No function or no display.						
			.5 Current consumption exceeds product specifications.						
		1.6 OLED viewir		etec	t.		$\mathcal{D}$		
		1.7 Mixed produ 1.8 Contrast def	•••						
						Y			
02	Black or	2.1 White and b	ack spots	on o	display $\leq 0.25r$	mm, no more than			
	white	three white or bl				Y			
	spots on	2.2 Densely spa	ced: No m	ore	than two spots	s or lines within	2.5		
	OLED	3mm.					2.0		
	(display								
03	only) OLED	3.1 Round type	۰As						
00	black	following drawin			SIZE	Acceptable Q			
	spots,	$\Phi = (x + y) / 2$	9			TY			
	white	X			Ф≦0.10	Accept no			
	spots,					dense			
	contamina		Y		0.10<	2	2.5		
	tion				Ф≦0.20				
	(non-displ ay)				0.20<	1			
	ay)				Φ≦0.25				
			1	6	0.25<Φ	0			
		3.2 Line type : (/		<u> </u>	•••				
	A	( ÷	Length		dth	Acceptable Q TY			
		$\sim$ $\downarrow$ $\underline{w}$			≦0.02	Accept no dense	2.5		
		→ <sub>L</sub> +	L≦3.0	-	$02 < W \le 0.03$	2	2.5		
			L≦2.5		$3 < W \le 0.05$				
			<u> </u>	0.0	)5 <w< td=""><td>As round type</td><td></td></w<>	As round type			
04	Polarizer								
	bubbles	If bubbles are vi			ze Φ	Acceptable Q TY			
		judge using blac			≦0.20	Accept no dense			
		specifications, n to find, must che			$20 < \Phi \le 0.50$	3	2.5		
		specify direction			50<Φ≦1.00	2	0,0		
			•	1.0	Φ>00	0			
				То	tal Q TY	3			

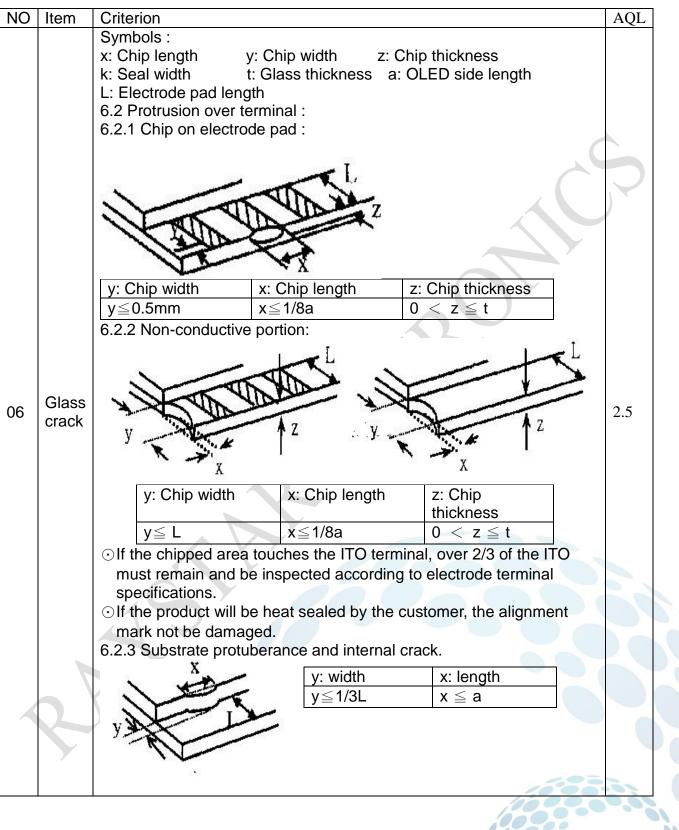


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NO	Item	Criterion		AQL	
05	Scratches	Follow NO.3 OLED b	plack spots, white spo	ots, contamination	
			t: Glass thickness	Chip thickness a: OLED side length	
		6.1 General glass ch 6.1.1 Chip on panel	nip : surface and crack be <b>X</b>	tween panels:	<sup>1</sup>
	Chipped glass				
06		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	2.5
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≦1/8a	2.0
<ul> <li>If there are 2 or more chips, x is total length of each chip.</li> <li>6.1.2 Corner crack:</li> </ul>				0	
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \le 1/2t$	Not over viewing area	x≦1/8a	
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≦1/8a	
		$\odot$ If there are 2 or m	ore chips, x is the tota	al length of each chip.	





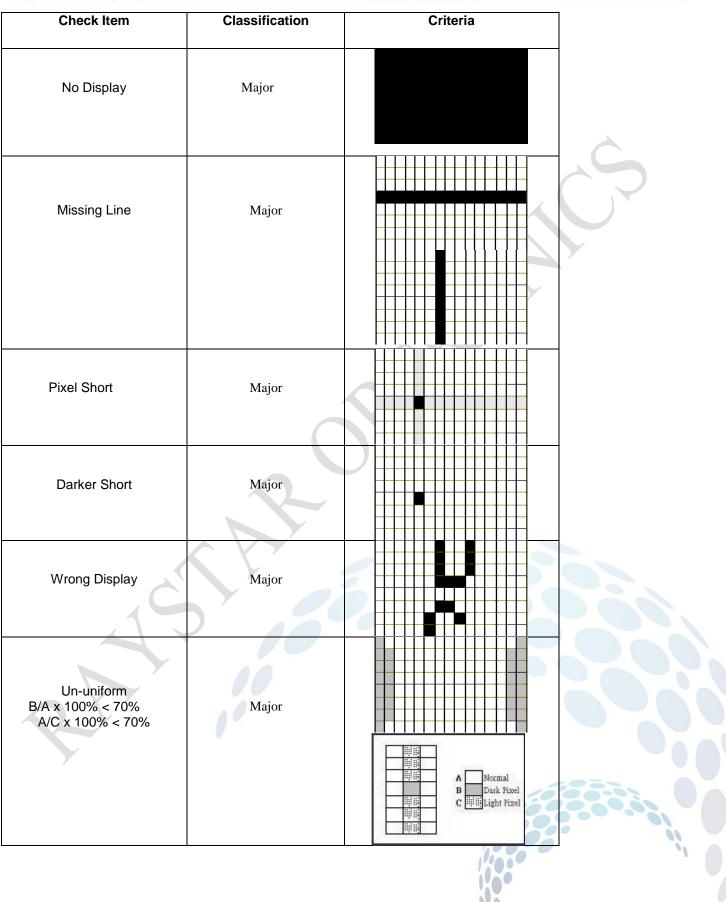


NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	
10	PCB、COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> </ul>	<ul> <li>2.5</li> <li>2.5</li> <li>0.65</li> <li>2.5</li> <li>0.65</li> <li>0.65</li> <li>2.5</li> </ul>
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65



NO	Item	Criterion	AQL
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on	2.5
		product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the	
		interface pin must be present or look as if it cause the	2.5
12		interface pin to sever.	)
12		12.6 The residual rosin or tin oil of soldering (component or	2.5
		chip component) is not burned into brown or black color.	0.65
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 OLED pin loose or missing pins.	
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to	
		product specification sheet.	







### **11.Precautions in use of OLED Modules**

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Raystar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) Raystar has the right to upgrade or modify the product function.

#### 11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.

\* Scotch Mending Tape No. 810 or an equivalent

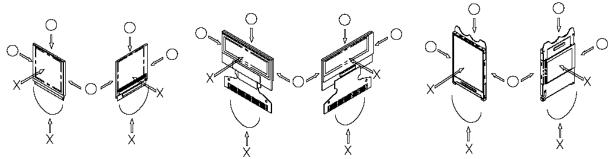
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- \* Water
- \* Ketone
- \* Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display modules.
  - \* Pins and electrodes
  - \* Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the



System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
  - \* Be sure to make human body grounding when handling OLED display modules.
  - \* Be sure to ground tools to use or assembly such as soldering irons.

\* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.

\* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

#### 11.2. Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. (We recommend you to store these modules in the packaged state when they were shipped from Raystar. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

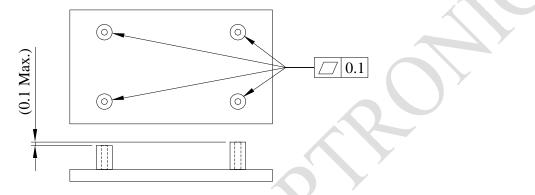
#### 11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.

\* Connection (contact) to any other potential than the above may lead to rupture of the IC.

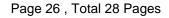


- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.
- (11) The module should be fixed balanced into the housing, or the module may be twisted.



#### 11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.





		Page: 1		
Modu	le Sampl	e Estimate Feedback Sheet		
Module Number :				
1 <u> Panel Specification</u> :				
1. Panel Type :	Pass	□NG ,		
2. Numbers of Pixel :	Pass	□NG ,		
3. View Area :	Pass	□NG ,		
4. Active Area :	Pass	□NG ,		
5.Emitting Color :	Pass	□NG ,		
6.Uniformity:	□Pass	□NG ,		
7.Operating	Pass	□NG ,		
Temperature :		Y Y		
8.Storage Temperature :	Pass	□NG ,		
9.Others :				
2 · Mechanical Specificati	on :			
1. PCB Size :	□Pass	□NG ,		
2.Frame Size :	□Pass	□NG ,		
3.Materal of Frame :	□Pass	□NG ,		
4.Connector Position :	□Pass	□NG ,		
5.Fix Hole Position :	□Pass	□NG ,		
6. Thickness of PCB :	□Pass	□NG ,		
7. Height of Frame to	□Pass	□NG ,		
PCB :				
8.Height of Module :	□Pass	□NG ,		
9.Others :	□Pass	□NG ,		
3 · Relative Hole Size :				
1.Pitch of Connector :	□Pass	□NG ,		
2.Hole size of	□Pass	□NG ,		
Connector :				
3.Mounting Hole size :	□Pass	□NG ,		
4.Mounting Hole Type :	□Pass	□NG ,		
5.Others :	□Pass	□NG ,		

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Module Number :				
4 · Electronic Characteristics of Module				
1.Input Voltage:	□Pass	□NG ,		
2.Supply Current :	□Pass	□NG ,		
3.Driving Voltage for OLED :	□Pass	□NG ,		
4.Contrast for OLED :	□Pass	□NG ,		
5.Negative Voltage Output :	□Pass	□NG ,		
6.Interface Function :	□Pass	□NG ,		
7.ESD test :	□Pass	□NG ,		
8.Others :	□Pass	□NG ,		
E Summonu'				

5 \ <u>Summary</u> :

Sales signature : \_\_\_\_\_ Customer Signature : \_\_\_\_\_

Date : / /